

IN THE UNITED STATES  
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicant: Vierk et al.

Case: A-66435/JAS/MSS

Serial No.: 09/314,262

Filed: May 18, 1999

Group Art Unit: 1773

Examiner: S. Resan

Title: HIGH MODULUS AND HIGH DAMPING PLASTIC COMPOSITE DISC  
SUBSTRATE FOR IMPROVED SERVO CONTROL BY INJECTION AND  
CO-INJECTION MOLDING

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

S I R:

PRELIMINARY AMENDMENT

In response to the Office Action dated September 13, 2001, please amend  
the above-identified patent application as follows:

IN THE CLAIMS

Please rewrite claims 1, 5, 14, 17 and 19.

(Twice Amended) A substrate for use in a data storage system,  
comprising:

at least one plastic composite material exhibiting a modulus of about  
350 kpsi or greater;

AET  
#10/B  
2/26/02

FAX RECEIVED  
DEC 13 2001  
GROUP 1700  
OFFICIAL